

600V N-Channel MOSFET

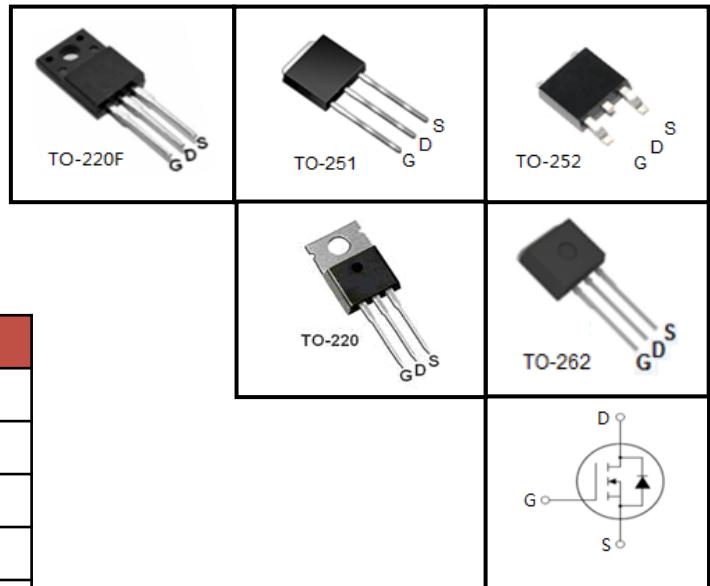
FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information		
Device	Package	Marking
HF2N60	TO-220F	HF2N60
HP2N60	TO-220	HP2N60
HU2N60	TO-251	HU2N60
HD2N60	TO-252	HD2N60
HB2N60	TO-262	HB2N60



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value					Unit
		TO-220F	TO-262	TO-220	TO-251	TO-252	
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}			600			V
Continuous Drain Current	I_D			2			A
Pulsed Drain Current (note1)	I_{DM}			8			A
Gate-Source Voltage	V_{GSS}			± 30			V
Single Pulse Avalanche Energy (note2)	E_{AS}			28.8			mJ
Avalanche Current (note1)	I_{AS}			2.4			A
Repetitive Avalanche Energy (note1)	E_{AR}			17.28			mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	20		25			W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	$-55\text{--}+150$					$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value					Unit
		TO-220F	TO-262	TO-251	TO-252	TO-220	
Thermal Resistance, Junction-to-Case	R_{thJC}	6.25		5			$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5		60			

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 30\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	3.0	--	4.0	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 1.0\text{A}$	--	3.5	4.2	Ω
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	249.5	--	pF
Output Capacitance	C_{oss}		--	30	--	
Reverse Transfer Capacitance	C_{rss}		--	4.2	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 480\text{V}, I_D = 2.0\text{A}, V_{\text{GS}} = 10\text{V}$	--	11	--	nC
Gate-Source Charge	Q_{gs}		--	1.55	--	
Gate-Drain Charge	Q_{gd}		--	6.15	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_D = 2.0\text{A}, R_G = 25 \Omega$	--	33.6	--	ns
Turn-on Rise Time	t_r		--	7.2	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	64	--	
Turn-off Fall Time	t_f		--	31.2	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	2	A
Pulsed Diode Forward Current	I_{SM}		--	--	8	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 1.0\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.4	V
Reverse Recovery Time	t_{rr}	$V_{\text{GS}} = 0\text{V}, I_S = 2.0\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	490	--	ns
Reverse Recovery Charge	Q_{rr}		--	0.6	--	μC

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 10.0mH, $V_{\text{DD}} = 50\text{V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

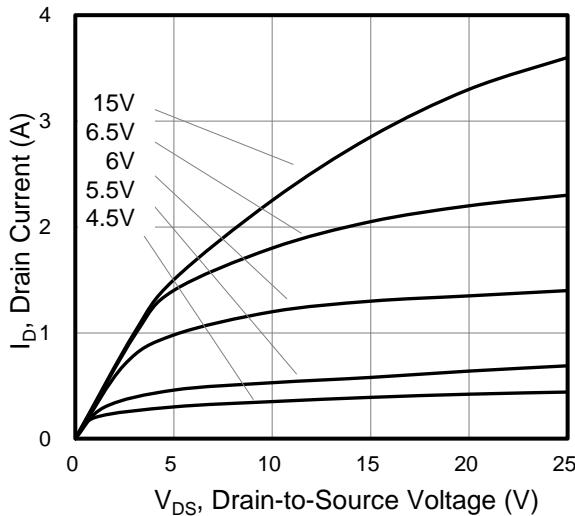


Figure 2. Body Diode Forward Voltage

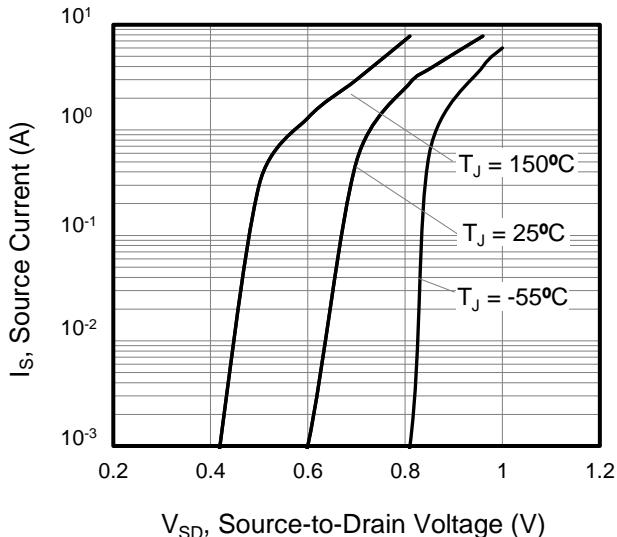
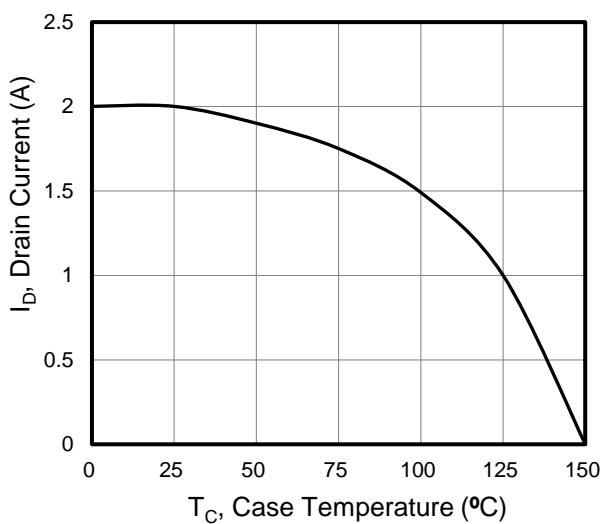


Figure 3. Drain Current vs. Temperature



**Figure 4. Power Dissipation vs. Temperature
TO-251, TO-252**

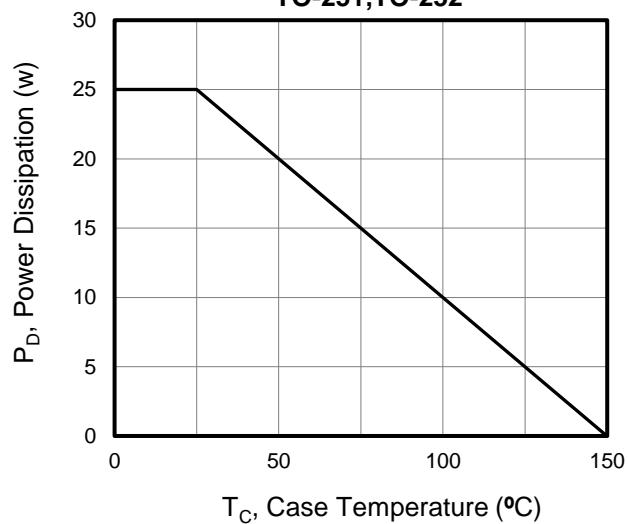


Figure 5. Transfer Characteristics

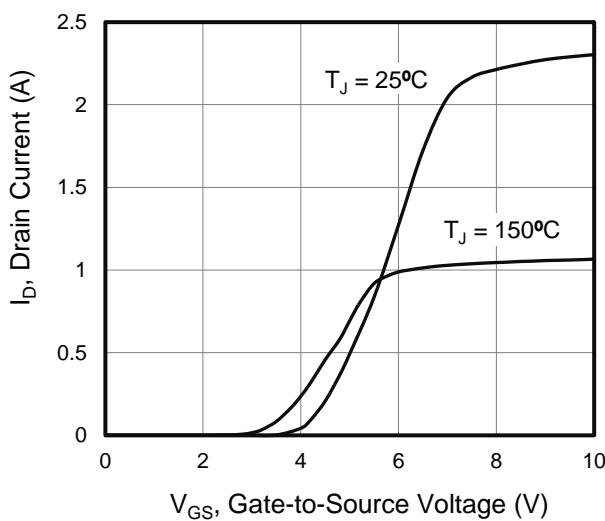
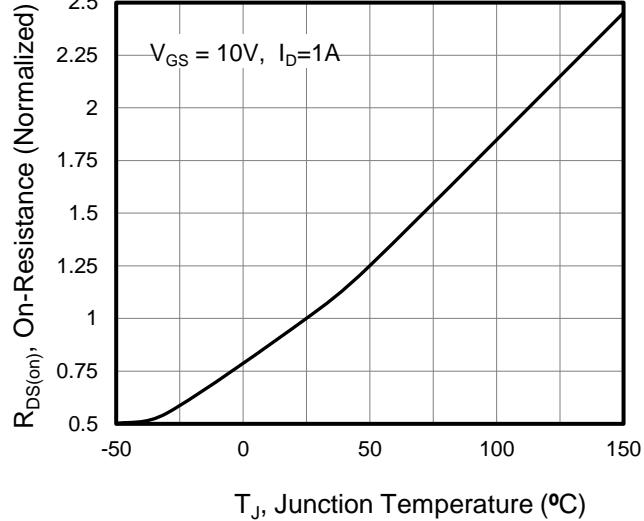


Figure 6. On-Resistance vs. Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Capacitance

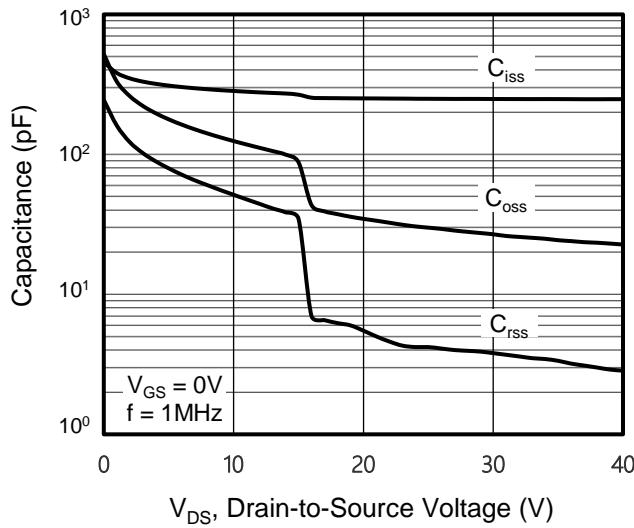
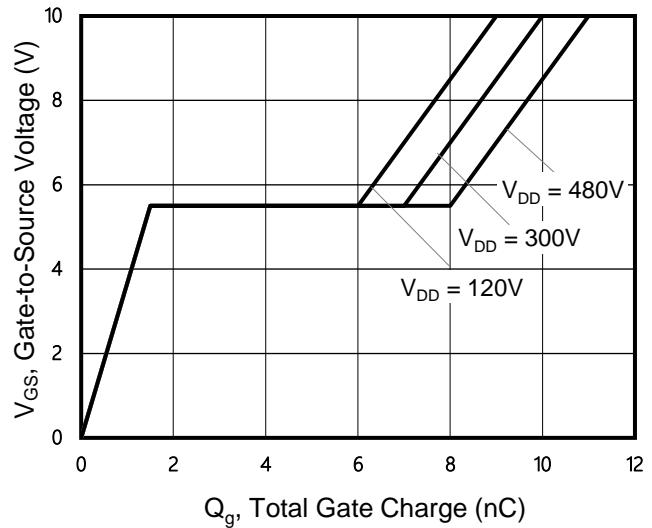
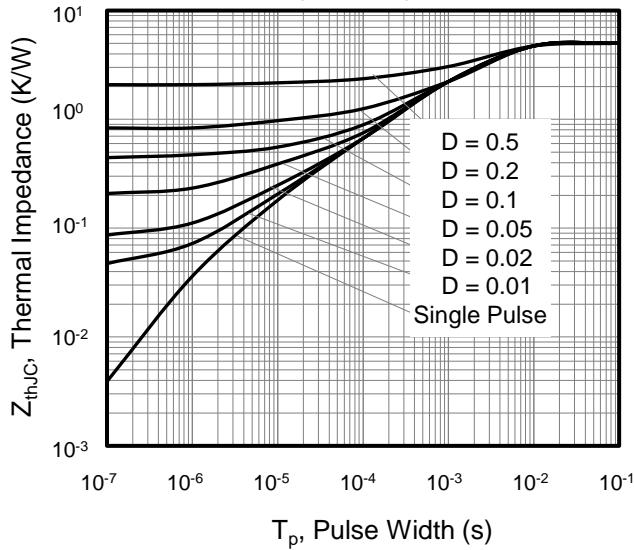


Figure 8. Gate Charge



**Figure 9. Transient Thermal Impedance
TO-251, TO-252 , TO-220**



**Figure 10. Transient Thermal Impedance
TO-220F ,TO-126F**

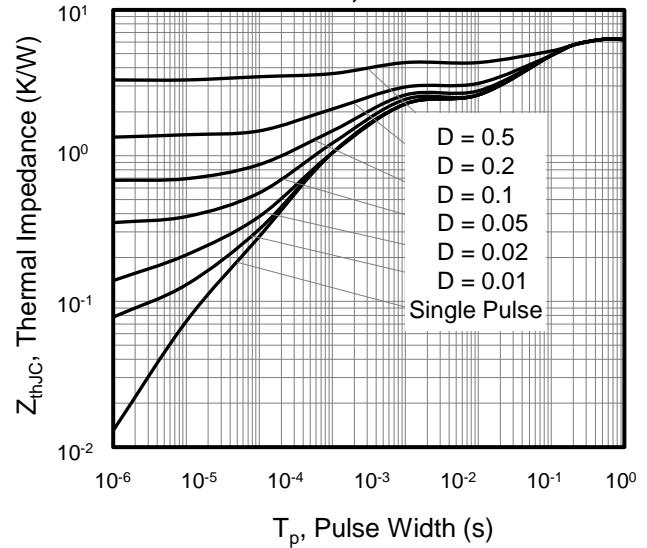


Figure A: Gate Charge Test Circuit and Waveform

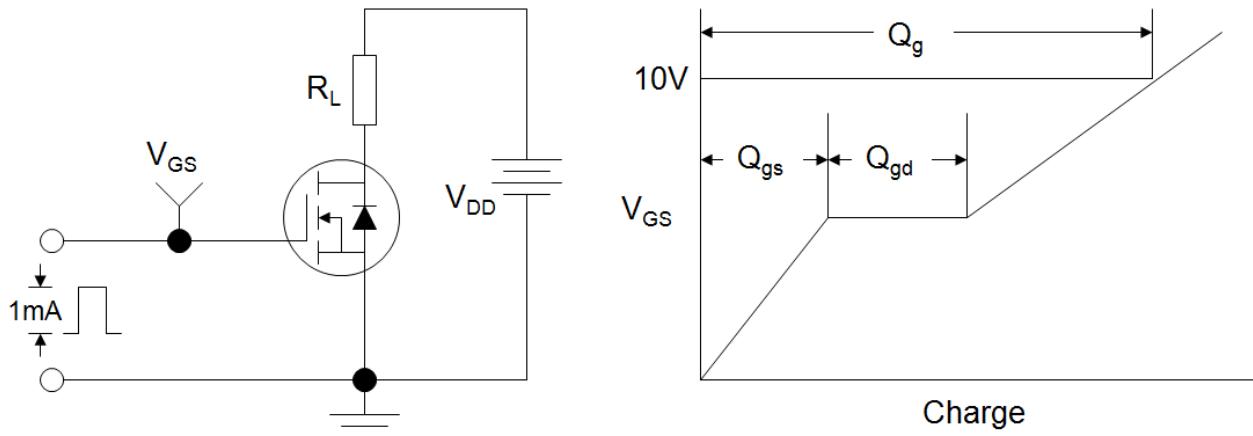


Figure B: Resistive Switching Test Circuit and Waveform

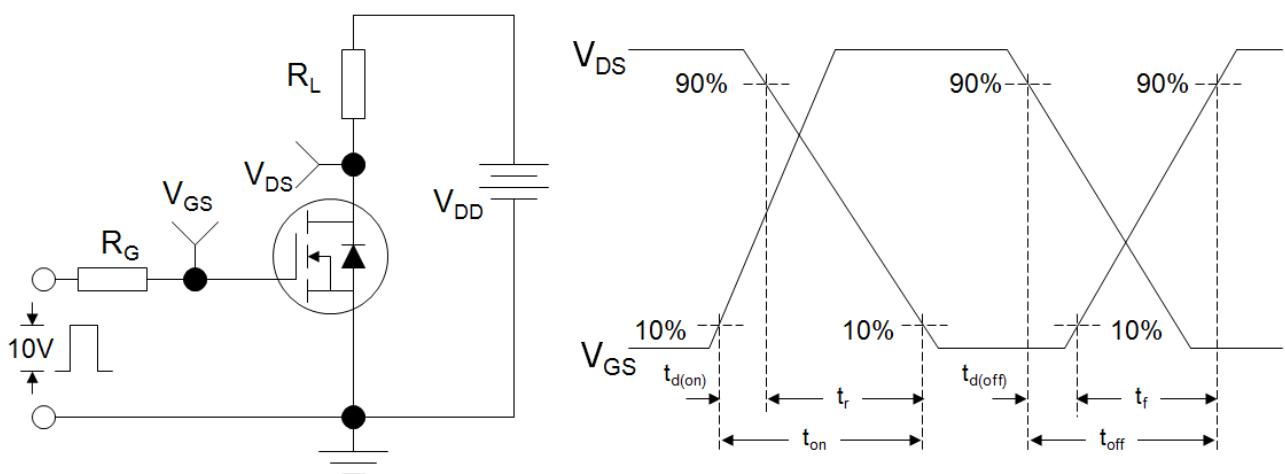
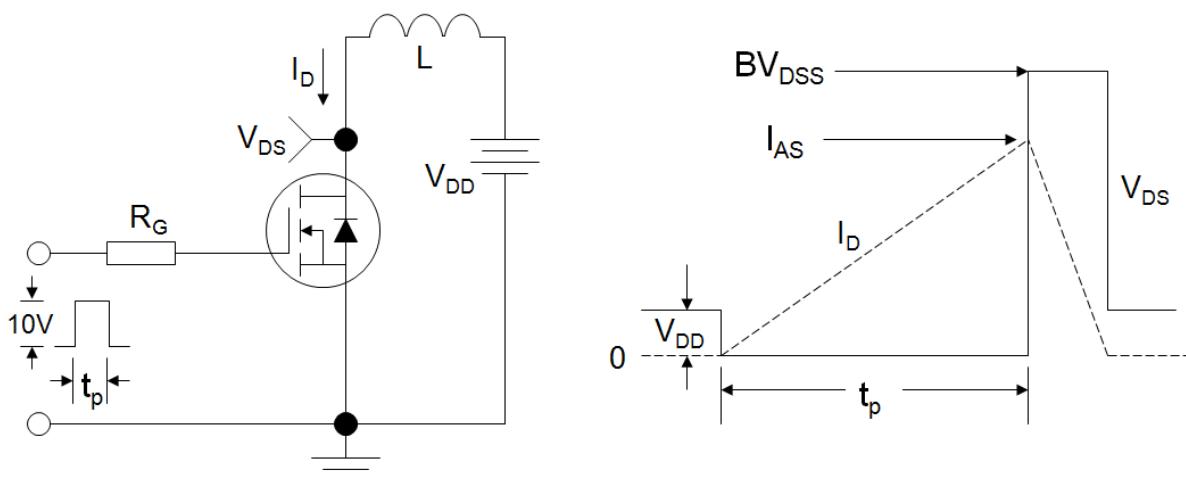
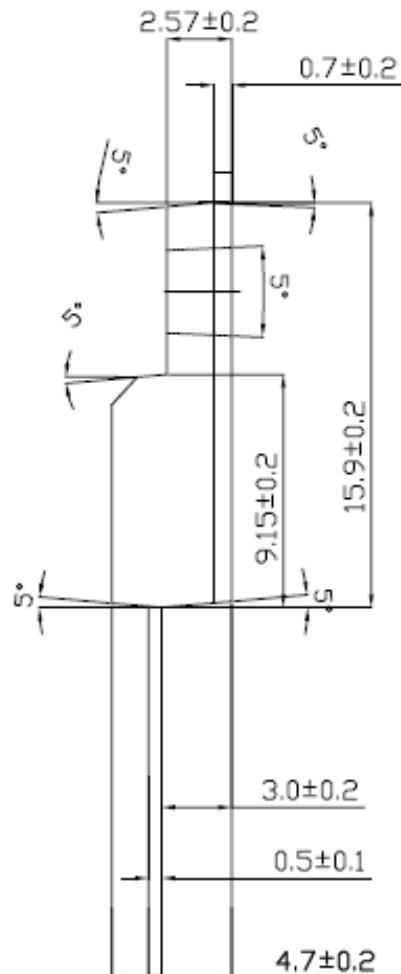
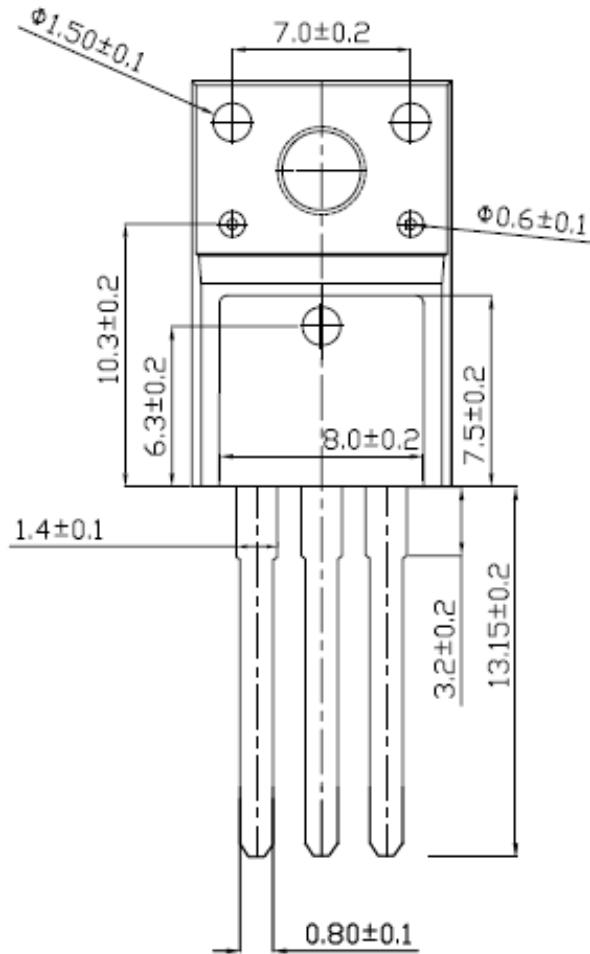


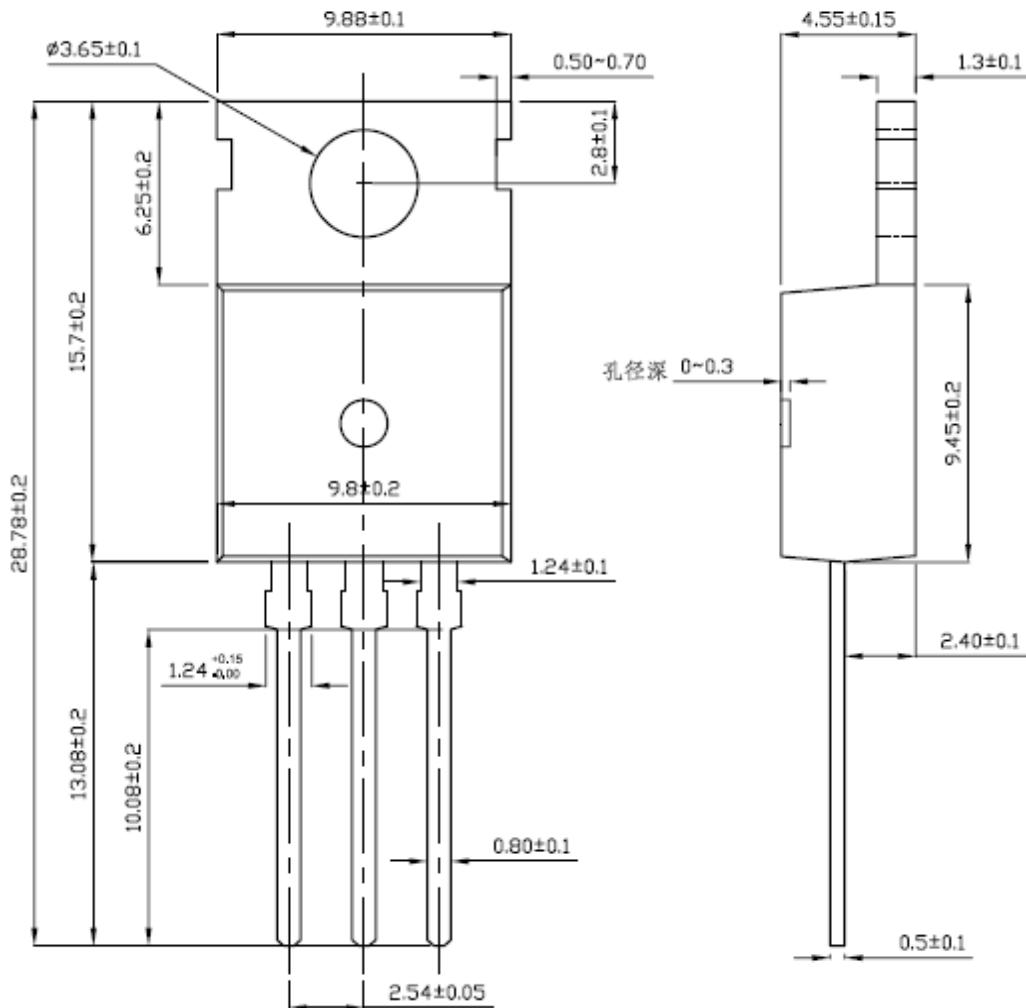
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



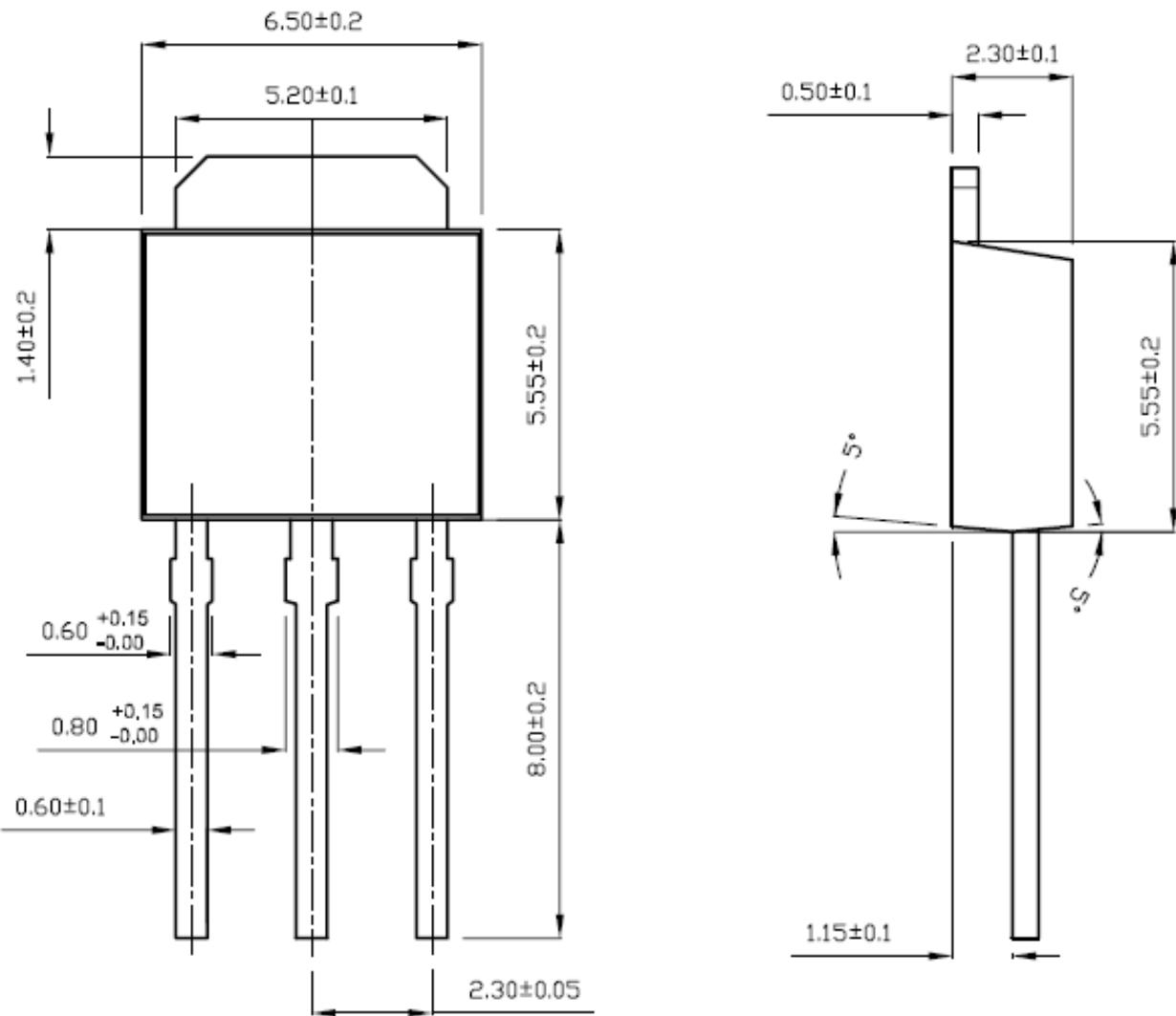
TO-220F



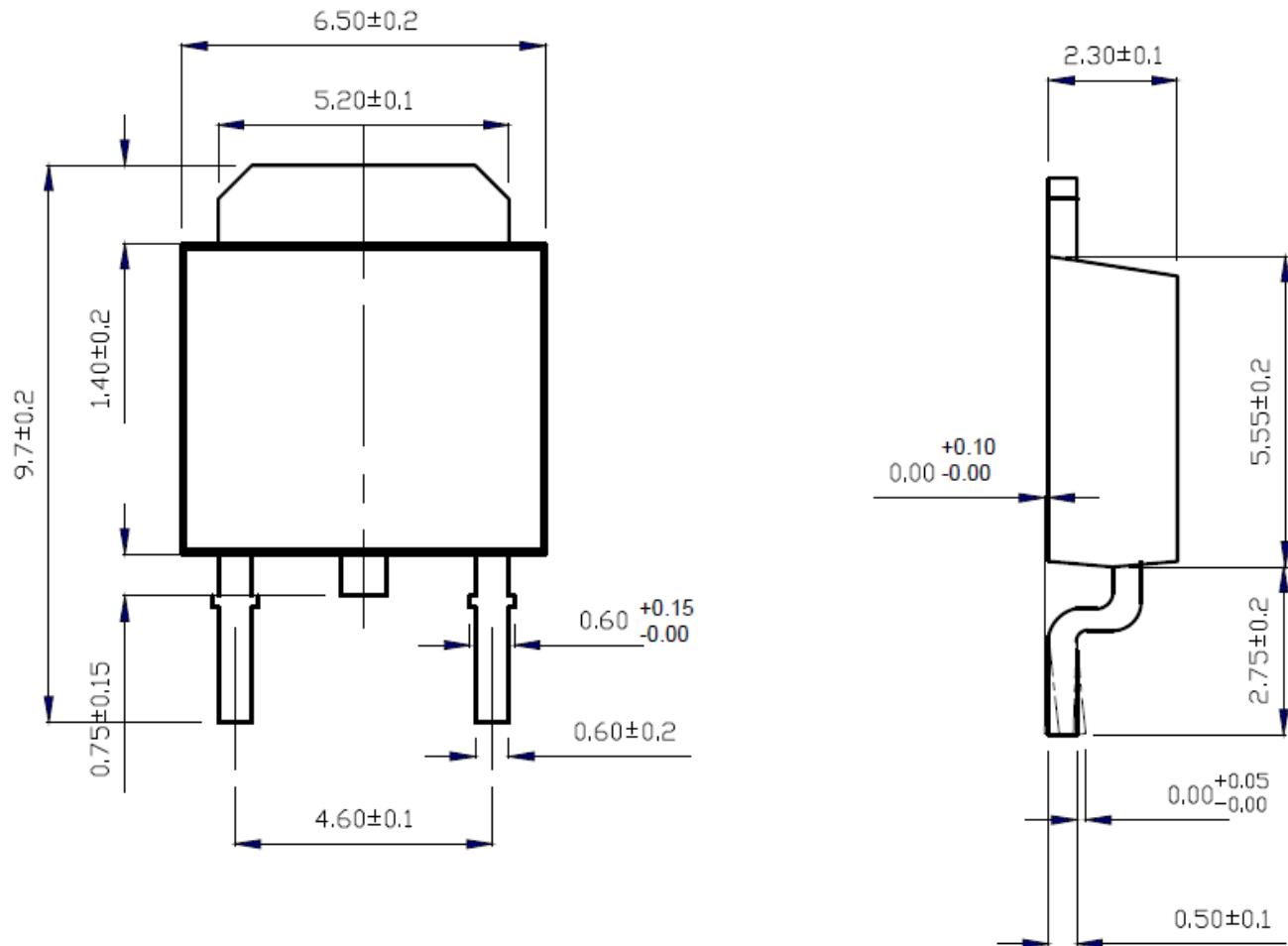
TO-220



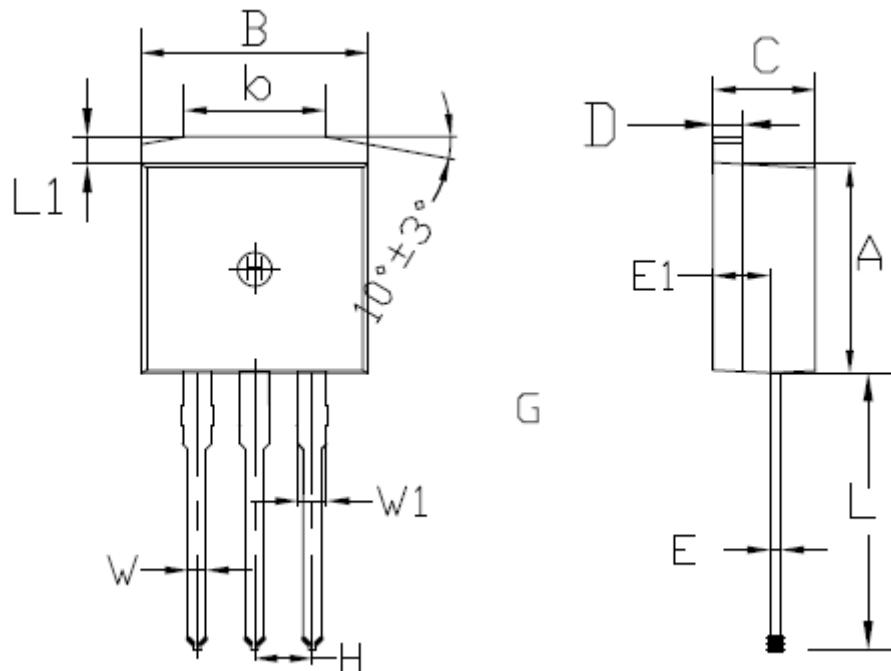
TO-251



TO-252



TO-262



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	8.80	9.30
B	9.70	10.30
C	4.25	4.75
D	1.20	1.45
E	0.40	0.60
L	12.25	13.75
L1	1.15	1.45
E1	2.40	2.60
W	0.80	0.82
W1	1.20	1.30
H	2.54TYP	
b	5.50	6.50